

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT6549565

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	DEJIE TAO	02/10/2021
	YILIANG WU	02/08/2021
	LANANH PHAM	02/08/2021
	LEI WANG	02/09/2021
	TING GAO	02/08/2021
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	TE CONNECTIVITY SERVICES GMBH	
<b>Street Address:</b>	MUHLENSTRASSE 26	
<b>City:</b>	SCHAFFHAUSEN	
<b>State/Country:</b>	SWITZERLAND	
<b>Postal Code:</b>	8200	
<b>PROPERTY NUMBERS Total: 1</b>		
<b>Property Type</b>	<b>Number</b>	
<b>Application Number:</b>	17161128	
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>	(302)633-2776	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	13026332740	
<b>Email:</b>	ipdocket.wilm@te.com	
<b>Correspondent Name:</b>	THE WHITAKER LLC	
<b>Address Line 1:</b>	4550 LINDEN HILL ROAD	
<b>Address Line 4:</b>	WILMINGTON, DELAWARE 19808-2952	
<b>ATTORNEY DOCKET NUMBER:</b>	TE-03490/001463.00249	
<b>NAME OF SUBMITTER:</b>	BRUCE J. WOLSTONCROFT	
<b>SIGNATURE:</b>	/Bruce J. Wolstoncroft/	
<b>DATE SIGNED:</b>	02/12/2021	
	This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 5</b>		

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## COMBINED DECLARATION AND ASSIGNMENT

As a below named and signing inventor, **I hereby declare that:**

this declaration is directed to inventions and improvements disclosed in:

- ☐ the attached application, or  
☒ United States application or PCT international application number 17/161,128 filed on January 28, 2021,

entitled "HYBRID SILICONE COMPOSITE FOR HIGH TEMPERATURE APPLICATIONS"  
("the APPLICATION");

the APPLICATION was made or authorized to be made by me;

I believe that I am the original inventor or an original joint inventor of a claimed invention in the APPLICATION;

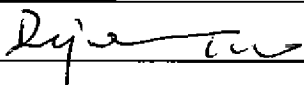
I have reviewed and understand the contents of the APPLICATION, including the claims, and I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. §1.56; and

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both.

As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:

TE Connectivity Services GmbH ("ASSIGNEE"), a corporation organized and existing under and by virtue of the laws of Switzerland, having its principal place of business at Mühlenstrasse 26, 8200 Schaffhausen Switzerland

for a valuable consideration, the receipt of which is hereby acknowledged, **I do hereby sell, assign, transfer, and set over unto the said ASSIGNEE, its successors and assigns**, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America, its territories and possessions, but also for, to and in all other countries, including all priority rights under the International Convention, and all reissues, re-examinations, renewals or extensions thereof; and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment.

Legal Name	Signature	Date
Dejie TAO		2/10/2021
Yiliang WU		
Lananh PHAM		
Lei WANG		
Ting GAO		

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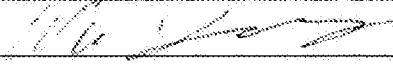
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Legal Name	Signature	Date
Dejie TAO		
Yiliang WU		Feb 8, 2021
Lananh PHAM		
Lei WANG		
Ting GAO		

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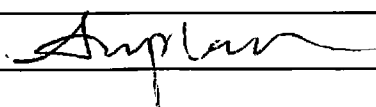
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Legal Name	Signature	Date
Dejie TAO		
Yiliang WU		
Lananh PHAM		02/08/2021
Lei WANG		
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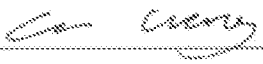
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Legal Name	Signature	Date
Dejie TAO		
Yiliang WU		
Lananh PHAM		
Lei WANG		02-09-2021
Ting GAO		

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